

IN THE CLAIMS:

Claims 1-9, and 12-15 have been amended. All of the pending claims 1 through 15 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Currently Amended) A heat sink for assembly with a semiconductor device component, comprising:

a heat transfer element configured to be secured to the semiconductor device component and including at least one ~~non-~~nonlinear passageway therethrough.

2. (Currently Amended) The heat sink of claim 1, wherein at least a portion of said the heat transfer element comprises a plurality of superimposed, contiguous, mutually adhered layers of thermally conductive material.

3. (Currently Amended) The heat sink of claim 2, wherein said the thermally conductive material comprises a metal.

4. (Currently Amended) The heat sink of claim 3, wherein said the metal comprises copper, aluminum, tungsten, or titanium.

5. (Currently Amended) The heat sink of claim 2, wherein said the thermally conductive material comprises a ceramic or a glass.

6. (Currently Amended) The heat sink of claim 1, wherein said the heat transfer element comprises a plurality of particles that are secured to one another.

7. (Currently Amended) The heat sink of claim 6, wherein adjacent ones of said the particles are sintered together.

8. (Currently Amended) The heat sink of claim 6, wherein adjacent ones of said the particles are secured together with a binder.

9. (Currently Amended) The heat sink of claim 2, wherein at least some of said the plurality of superimposed, contiguous, mutually adhered layers comprise sheets of said the thermally conductive material.

10. (Original) The heat sink of claim 9, wherein adjacent sheets are secured together with an adhesive material.

11. (Original) The heat sink of claim 9, wherein adjacent sheets are thermally bonded together.

12. (Currently Amended) The heat sink of claim 1, wherein said the at least one non-nonlinear passageway is configured to permit airflow therethrough.

13. (Currently Amended) The heat sink of claim 1, further comprising a heat dissipation element adjacent to said the heat transfer element and extending to a location remote from the semiconductor device component.

14. (Currently Amended) The heat sink of claim 13, wherein at least a portion of said the heat dissipation element comprises a plurality of superimposed, contiguous, mutually adhered layers of thermally conductive material.

15. (Currently Amended) The heat sink of claim 14, wherein said the heat dissipation element includes a plurality of fins.